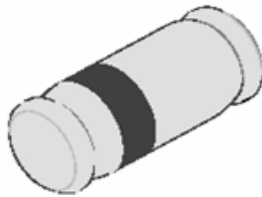




SEMICONDUCTOR Small Signal Products

MATERIAL CONTENT LIST

PACKAGE FAMILY: **SOD-80 MiniMELF**
 DATE: **6-May-2010**
 REVISION: **11**



**RoHS
COMPLIANT**



MATERIAL CONTENT					
Part	Material	CAS N°	weight mg	% of weight	ppm of total weight
Plug 56.8%	Fe	7439-89-6	7.7	44.0%	249981
	Cu	7440-50-8	4.2	24.0%	136353
	Ni	7440-02-0	5.6	32.0%	181804
	CuO	1317-38-0	Trace		
	TOTAL		17.50		
Terminal finish 1.6%	Sn	7440-31-5	0.468	97.5%	15194
	Ag	7440-22-4	0.012	2.5%	390
	TOTAL		0.48		
Package Glass 41.2%	PbO *)	1317-36-8	7.783	61.3%	252661
	SiO ₂	14808-60-7	4.049	31.9%	131443
	K ₂ O	12136-45-7	0.445	3.5%	14431
	Na ₂ O	1313-59-3	0.003	0.02%	82
	Al ₂ O ₃	1344-28-1	0.015	0.12%	495
	B ₂ O ₃	1303-86-2	0.381	3.0%	12369
	Sb ³⁺ **)	7440-36-0	0.025	0.2%	825
	TOTAL		12.700		
Silicon Chip 0.3%	Si	7440-21-3	0.0741	80.19%	2406
	Ag	7440-22-4	0.0153	16.56%	497
	SiO ₂	14808-60-7	0.0015	1.62%	49
	PbO *)	1317-36-8	0.0013	1.41%	42
	Ni	7440-02-0	0.0002	0.22%	6
	TOTAL		0.092		
Ink 0.1%	Acrylate	Trade Secret	0.0136	45.18%	440
	Acrylat Monomer	Trade Secret	0.0066	21.84%	213
	Filler	Trade Secret	0.0066	21.89%	213
	Pigment	Trade Secret	0.0015	5.00%	49
	Diphenyl	75980-60-8	0.0006	2.00%	19
	Phosphinoxide	162881-26-7	0.0006	1.93%	19
	Diacylate	42978-66-5	0.0006	1.91%	19
	Cl	7782-50-5	0.00008	0.25%	2
	TOTAL		0.030		
Total weight			30.802		

Remark: Total weight range ± 10%
 *) Pb in glass of electronic components acc. ROHS exempted
 **) Antimony present as ion
 Reflow Soldering acc. J-STD-020D
 Material Analyses Reports available on request